



## Product Change Notification: MFOL-15XOSS098

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### Date:

25-Sep-2024

### Product Category:

32-Bit Microcontrollers

### Notification Subject:

CCB 7175 Initial Notice: Qualification of ATP7 as an additional assembly site for CEC1734-S0-I/2HW, CEC1734-I/2HW-MD, CEC1734-S0-I/2HW-TFLX-PROTO, CEC1734-S0-I/2HW-TCSM-PROTO, CEC1734-S0-I/2HW-TFLX, CEC1736-S0-I/2HW, CEC1736-S0-I/2HW-PROTO, CEC1736-S0-I/2HW-PROTO2, CEC1736-I/2HW-MD, CEC1736-S0-I/2HW-QU001, CEC1736-S0-I/2HW-TFLX-PROTO, CEC1736-S0-I/2HW-TFLX and CEC1736-S0-I/2HW-TCSM-PROTO catalog part numbers (CPN) available in 64L VFBGA (5.5x5.5x0.92mm) package.

### Affected CPNs:

**[MFOL-15XOSS098\\_Affected\\_CPN\\_09252024.pdf](#)**

**[MFOL-15XOSS098\\_Affected\\_CPN\\_09252024.csv](#)**

**PCN Status:** Initial Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of ATP7 as an additional assembly site for CEC1734-S0-I/2HW, CEC1734-I/2HW-MD, CEC1734-S0-I/2HW-TFLX-PROTO, CEC1734-S0-I/2HW-TCSM-PROTO, CEC1734-S0-I/2HW-TFLX, CEC1736-S0-I/2HW, CEC1736-S0-I/2HW-PROTO, CEC1736-S0-I/2HW-PROTO2, CEC1736-I/2HW-MD, CEC1736-S0-I/2HW-QU001, CEC1736-S0-I/2HW-TFLX-PROTO, CEC1736-S0-I/2HW-TFLX and CEC1736-S0-I/2HW-TCSM-PROTO catalog part numbers (CPN) available in 64L VFBGA (5.5x5.5x0.92mm) package.

### Pre and Post Summary Changes:

	Pre Change	Post Change

<b>Assembly Site</b>		Amkor Assembly & Test (Shanghai) Co., LTD/ (ANAC)	Amkor Assembly & Test (Shanghai) Co., LTD/ (ANAC)	Amkor Technology Philippines (P3/P4), INC. (ATP7)
<b>Substrate</b>	Core Material	HL832NXA	HL832NXA	HL832NXA
	SM Material	AUS320	AUS320	AUS320
<b>Wire Material</b>		CuPdAu	CuPdAu	CuPdAu
<b>Die Attach Material</b>	Die #1*	EM760L2-P	EM760L2-P	EM760L2-P
	Die #2*	EM760L2-P	EM760L2-P	EM760L2-P
	Die #3**	ATB-F125E	ATB-F125E	ATB-F125E
<b>Mold Compound</b>		G750E	G750E	G770FE
<b>Solder Ball Material</b>		SAC305	SAC305	SAC305

Note\*: Die 1 and Die 2 is only applicable to CEC1734-S0-I/2HW, CEC1734-I/2HW-MD, CEC1734-S0-I/2HW-TFLX-PROTO, CEC1734-S0-I/2HW-TCSM-PROTO, and CEC1734-S0-I/2HW-TFLX catalog part numbers using the same die attach material (EM760L2-P).

Note\*\*: Die 1, Die 2, and Die 3 are only applicable to CEC1736-S0-I/2HW, CEC1736-S0-I/2HW-PROTO, CEC1736-S0-I/2HW-PROTO2, CEC1736-I/2HW-MD, CEC1736-S0-I/2HW-QU001, CEC1736-S0-I/2HW-TFLX-PROTO, CEC1736-S0-I/2HW-TFLX, and CEC1736-S0-I/2HW-TCSM-PROTO catalog part numbers using EM760L2-P and ATB-F125E die attach material.

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve on-time delivery by qualifying ATP7 as an additional assembly site.

**Change Implementation Status:** In Progress

**Estimated Qualification Completion Date:** April 2025

**Note:** Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Timetable Summary:**

	September 2024					>	April 2025				
Work Week	36	37	38	39	40		14	15	16	17	18
Initial PCN Issue Date				X							
Qual Report Availability											X
Final PCN Issue Date											X

**Method to Identify Change:** Traceability Code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** September 25, 2024: Issued initial notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

**Attachments:**

**[PCN\\_MFOL-15XOSS098\\_Qual\\_Plan.pdf](#)**

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

**Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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- CEC1734-I/2HW-MD
- CEC1734-S0-I/2HW-TFLX-PROTO
- CEC1734-S0-I/2HW-TCSM-PROTO
- CEC1734-S0-I/2HW-TFLX
- CEC1736-S0-I/2HW
- CEC1736-S0-I/2HW-PROTO
- CEC1736-S0-I/2HW-PROTO2
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